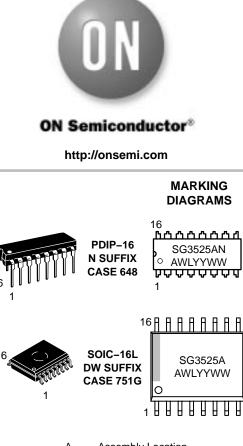
Pulse Width Modulator Control Circuit

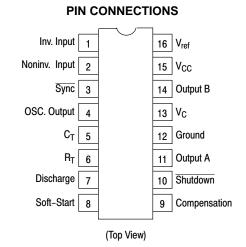
The SG3525A pulse width modulator control circuit offers improved performance and lower external parts count when implemented for controlling all types of switching power supplies. The on-chip +5.1 V reference is trimmed to $\pm 1\%$ and the error amplifier has an input common-mode voltage range that includes the reference voltage, thus eliminating the need for external divider resistors. A sync input to the oscillator enables multiple units to be slaved or a single unit to be synchronized to an external system clock. A wide range of deadtime can be programmed by a single resistor connected between the CT and Discharge pins. This device also features built-in soft-start circuitry, requiring only an external timing capacitor. A shutdown pin controls both the soft-start circuitry and the output stages, providing instantaneous turn off through the PWM latch with pulsed shutdown, as well as soft-start recycle with longer shutdown commands. The under voltage lockout inhibits the outputs and the changing of the soft-start capacitor when V_{CC} is below nominal. The output stages are totem-pole design capable of sinking and sourcing in excess of 200 mA. The output stage of the SG3525A features NOR logic resulting in a low output for an off-state.

Features

- 8.0 V to 35 V Operation
- 5.1 V \pm 1.0% Trimmed Reference
- 100 Hz to 400 kHz Oscillator Range
- Separate Oscillator Sync Pin
- Adjustable Deadtime Control
- Input Undervoltage Lockout
- Latching PWM to Prevent Multiple Pulses
- Pulse-by-Pulse Shutdown
- Dual Source/Sink Outputs: ±400 mA Peak
- Pb–Free Packages are Available*



- A = Assembly Location WL = Wafer Lot YY = Year
- WW = Work Week



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

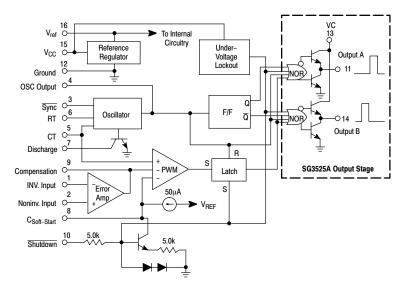


Figure 1. Representative Block Diagram

ORDERING INFORMATION

Device	Package	Shipping [†]
SG3525AN	PDIP-16	25 Units / Rail
SG3525ANG	PDIP-16 (Pb-Free)	25 Units / Rail
SG3525ADW	SOIC-16L	47 Units / Rail
SG3525ADWG	SOIC-16L (Pb-Free)	47 Units / Rail
SG3525ADWR2	SOIC-16L	1000 Tape & Reel
SG3525ADWR2G	SOIC-16L (Pb-Free)	1000 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V _{CC}	+40	Vdc
Collector Supply Voltage	V _C	+40	Vdc
Logic Inputs		-0.3 to +5.5	V
Analog Inputs		–0.3 to $V_{\mbox{CC}}$	V
Output Current, Source or Sink	lo	±500	mA
Reference Output Current	I _{ref}	50	mA
Oscillator Charging Current		5.0	mA
Power Dissipation $T_A = +25^{\circ}C$ (Note 1) $T_C = +25^{\circ}C$ (Note 2)	PD	1000 2000	mW
Thermal Resistance, Junction-to-Air	R _{0JA}	100	°C/W
Thermal Resistance, Junction-to-Case	R _{θJC}	60	°C/W
Operating Junction Temperature	TJ	+150	°C
Storage Temperature Range	T _{stg}	-55 to +125	°C
Lead Temperature (Soldering, 10 seconds)	T _{Solder}	+300	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Derate at 10 mW/°C for ambient temperatures above +50°C.

2. Derate at 16 mW/°C for case temperatures above +25°C.

RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	8.0	35	Vdc
Collector Supply Voltage	V _C	4.5	35	Vdc
Output Sink/Source Current (Steady State) (Peak)	lo	0 0	±100 ±400	mA
Reference Load Current	I _{ref}	0	20	mA
Oscillator Frequency Range	f _{osc}	0.1	400	kHz
Oscillator Timing Resistor	R _T	2.0	150	kΩ
Oscillator Timing Capacitor	CT	0.001	0.2	μF
Deadtime Resistor Range	R _D	0	500	Ω
Operating Ambient Temperature Range	T _A	0	+70	°C

APPLICATION INFORMATION

Shutdown Options (See Block Diagram, page 2)

Since both the compensation and soft-start terminals (Pins 9 and 8) have current source pull-ups, either can readily accept a pull-down signal which only has to sink a maximum of 100 μ A to turn off the outputs. This is subject to the added requirement of discharging whatever external capacitance may be attached to these pins.

An alternate approach is the use of the shutdown circuitry of Pin 10 which has been improved to enhance the available shutdown options. Activating this circuit by applying a positive signal on Pin 10 performs two functions: the PWM latch is immediately set providing the fastest turn–off signal to the outputs; and a 150 μ A current sink begins to discharge the external soft–start capacitor. If the shutdown command is short, the PWM signal is terminated without significant discharge of the soft–start capacitor, thus, allowing, for example, a convenient implementation of pulse–by–pulse current limiting. Holding Pin 10 high for a longer duration, however, will ultimately discharge this external capacitor, recycling slow turn–on upon release.

Pin 10 should not be left floating as noise pickup could conceivably interrupt normal operation.

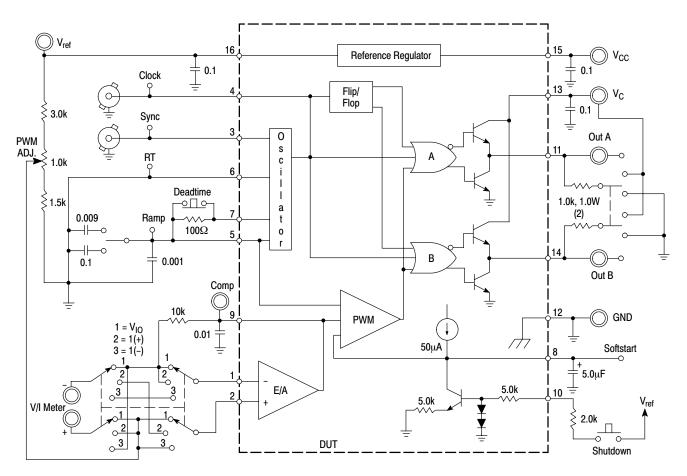
Characteristics	Symbol	Min	Тур	Max	Unit
REFERENCE SECTION	•	•		•	
Reference Output Voltage ($T_J = +25^{\circ}C$)	V _{ref}	5.00	5.10	5.20	Vdc
Line Regulation (+8.0 V \leq V _{CC} \leq +35 V)	Reg _{line}	-	10	20	mV
Load Regulation (0 mA \leq I _L \leq 20 mA)	Reg _{load}	-	20	50	mV
Temperature Stability	$\Delta V_{ref} / \Delta T$	-	20	-	mV
Total Output Variation Includes Line and Load Regulation over Temperature	ΔV_{ref}	4.95	_	5.25	Vdc
Short Circuit Current ($V_{ref} = 0 V$, $T_J = +25^{\circ}C$)	I _{SC}	-	80	100	mA
Output Noise Voltage (10 Hz \leq f \leq 10 kHz, T _J = +25°C)	V _n	-	40	200	μV_{rms}
Long Term Stability ($T_J = +125^{\circ}C$) (Note 4)	S	-	20	50	mV/kh
OSCILLATOR SECTION (Note 5, unless otherwise noted.)					
Initial Accuracy ($T_J = +25^{\circ}C$)		-	±2.0	±6.0	%
Frequency Stability with Voltage (+8.0 V \leq V _{CC} \leq +35 V)	$\frac{\Delta f_{OSC}}{D_{VCC}}$	-	±1.0	±2.0	%
Frequency Stability with Temperature	$\frac{\Delta f_{OSC}}{DT}$	-	±0.3	-	%
Minimum Frequency (R_T = 150 k Ω , C_T = 0.2 μ F)	f _{min}	-	50	-	Hz
Maximum Frequency ($R_T = 2.0 \text{ k}\Omega$, $C_T = 1.0 \text{ nF}$)	f _{max}	400	-	-	kHz
Current Mirror (I _{RT} = 2.0 mA)		1.7	2.0	2.2	mA
Clock Amplitude		3.0	3.5	-	V
Clock Width ($T_J = +25^{\circ}C$)		0.3	0.5	1.0	μs
Sync Threshold		1.2	2.0	2.8	V
Sync Input Current (Sync Voltage = +3.5 V)		-	1.0	2.5	mA
ERROR AMPLIFIER SECTION (V _{CM} = +5.1 V)	•				
Input Offset Voltage	V _{IO}	-	2.0	10	mV
Input Bias Current	I _{IB}	-	1.0	10	μΑ
Input Offset Current	I _{IO}	-	-	1.0	μΑ
DC Open Loop Gain ($R_L \ge 10 M\Omega$)	A _{VOL}	60	75	-	dB
Low Level Output Voltage	V _{OL}	-	0.2	0.5	V
High Level Output Voltage	V _{OH}	3.8	5.6	-	V
Common Mode Rejection Ratio (+1.5 V \leq V $_{CM}$ \leq +5.2 V)	CMRR	60	75	-	dB
Power Supply Rejection Ratio (+8.0 V \leq V _{CC} \leq +35 V)	PSRR	50	60	-	dB
PWM COMPARATOR SECTION					
Minimum Duty Cycle	DC _{min}	-	_	0	%
Maximum Duty Cycle	DC _{max}	45	49	-	%
Input Threshold, Zero Duty Cycle (Note 5)	V _{th}	0.6	0.9	-	V
Input Threshold, Maximum Duty Cycle (Note 5)	V _{th}	-	3.3	3.6	V
Input Bias Current	I _{IB}	-	0.05	1.0	μΑ

T_{low} = 0° T_{high} = +70°C
 Since long term stability cannot be measured on each device before shipment, this specification is an engineering estimate of average stability from lot to lot.
 Tested at f_{osc} = 40 kHz (R_T = 3.6 kΩ, C_T = 0.01 μF, R_D = 0 Ω).

ELECTRICAL CHARACTERISTICS (continued)

Characteristics	Symbol	Min	Тур	Max	Unit
SOFT-START SECTION				•	
Soft–Start Current (V _{shutdown} = 0 V)		25	50	80	μΑ
Soft-Start Voltage (V _{shutdown} = 2.0 V)		-	0.4	0.6	V
Shutdown Input Current (V _{shutdown} = 2.5 V)		-	0.4	1.0	mA
OUTPUT DRIVERS (Each Output, V _{CC} = +20 V)					-
Output Low Level (I _{sink} = 20 mA) (I _{sink} = 100 mA)	V _{OL}		0.2 1.0	0.4 2.0	V
Output High Level (I _{source} = 20 mA) (I _{source} = 100 mA)	V _{OH}	18 17	19 18		V
Under Voltage Lockout (V8 and V9 = High)	V _{UL}	6.0	7.0	8.0	V
Collector Leakage, V _C = +35 V (Note 6)	I _{C(leak)}	-	-	200	μΑ
Rise Time (C _L = 1.0 nF, T _J = 25° C)	t _r	-	100	600	ns
Fall Time (C _L = 1.0 nF, T _J = 25°C)	t _f	-	50	300	ns
Shutdown Delay (V _{DS} = +3.0 V, C _S = 0, T _J = +25°C)	t _{ds}	-	0.2	0.5	μs
Supply Current (V _{CC} = +35 V)	I _{CC}	-	14	20	mA

6. Applies to SG3525A only, due to polarity of output pulses.





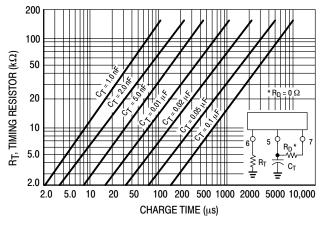


Figure 3. Oscillator Charge Time versus R_T

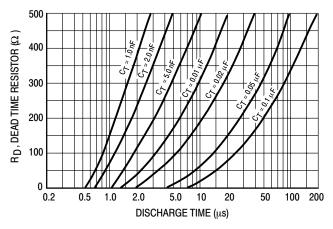
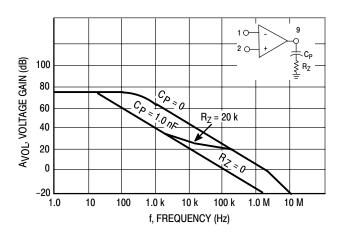


Figure 4. Oscillator Discharge Time versus R_D





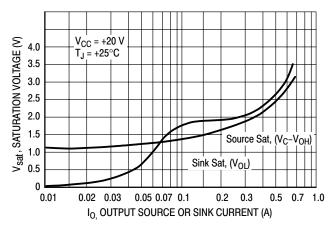


Figure 6. Output Saturation Characteristics

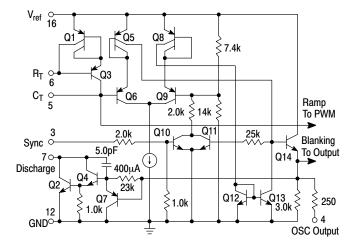
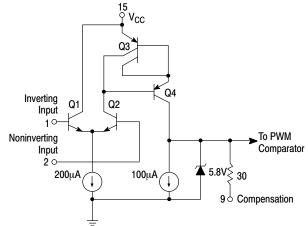


Figure 7. Oscillator Schematic





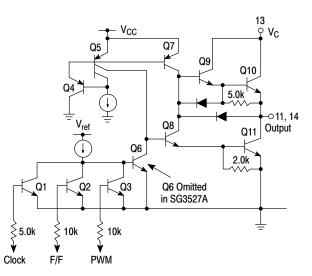
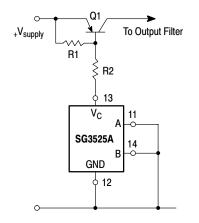
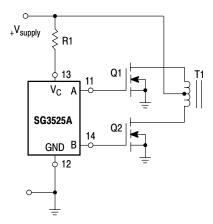


Figure 9. Output Circuit (1/2 Circuit Shown)



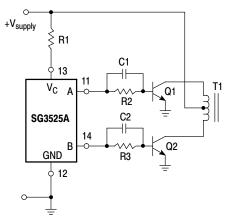
For single–ended supplies, the driver outputs are grounded. The V_C terminal is switched to ground by the totem–pole source transistors on alternate oscillator cycles.

Figure 10. Single–Ended Supply



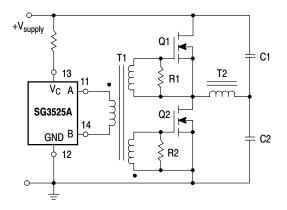
The low source impedance of the output drivers provides rapid charging of power FET input capacitance while minimizing external components.

Figure 12. Driving Power FETS



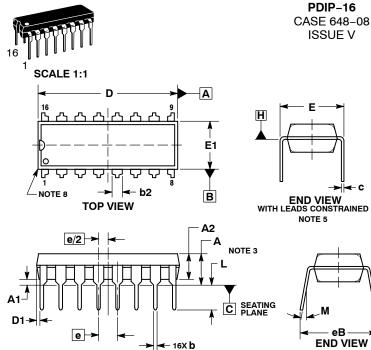
In conventional push-pull bipolar designs, forward base drive is controlled by R1-R3. Rapid turn-off times for the power devices are achieved with speed-up capacitors C1 and C2.

Figure 11. Push–Pull Configuration



Low power transformers can be driven directly by the SG3525A. Automatic reset occurs during deadtime, when both ends of the primary winding are switched to ground.

Figure 13. Driving Transformers in a Half–Bridge Configuration

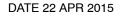


🕀 0.010 🕅 C A 🕅 B 🕅

STYLE 1: STYLE 2: PIN 1. COMMON DRAIN CATHODE CATHODE PIN 1. 2. 2. з. CATHODE 3. COMMON DRAIN COMMON DRAIN 4. 5. CATHODE 4. CATHODE 5. 6. CATHODE 6. COMMON DRAIN 7. CATHODE 7. COMMON DRAIN CATHODE COMMON DRAIN 8. 9. 8. 9. ANODE GATE 10. ANODE 10. SOURCE ANODE ANODE 11. 12. GATE SOURCE 11. 12. 13. ANODE 13. GATE 14. 15. ANODE ANODE 14. 15. SOURCE GATE 16. ANODE 16. SOURCE

SIDE VIEW

NOTE 6



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2
- 3.
- DIMENSIONING AND TOLERANGURA PER ASIME 114.300, 1994. CONTROLLING DIMENSION: INCHES. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACK-AGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH. 4.
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR 5. TO DATUM C.
- DIMENSION 6B IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE 6.
- 7
- LEADS, WHERE THE LEADS EXIT THE BODY. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE 8 CORNERS).

	INCHES MILLIMETERS				
DIM	MIN MAX MIN		MAX		
	IVITIN		IVITIN		
Α		0.210		5.33	
A1	0.015		0.38		
A2	0.115	0.195	2.92	4.95	
b	0.014	0.022	0.35	0.56	
b2	0.060	0.060 TYP		TYP	
С	0.008	0.014	0.20	0.36	
D	0.735	0.775	18.67	19.69	
D1	0.005		0.13		
Е	0.300	0.325	7.62	8.26	
E1	0.240	0.280	6.10	7.11	
е	0.100	BSC	2.54 BSC		
eВ		0.430		10.92	
L	0.115	0.150	2.92	3.81	
Μ		10°		10°	

GENERIC **MARKING DIAGRAM***

16 <u> </u>	1
XXXXXXXXXXXXXX	
• XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	
O AWLYYWWG	
᠋ᡝᢧᠣᠣᠣᠣᠥᠥ	Ţ

XXXXX = Specific Device Code

- = Assembly Location
- WL = Wafer Lot

А

- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " .", may or may not be present.

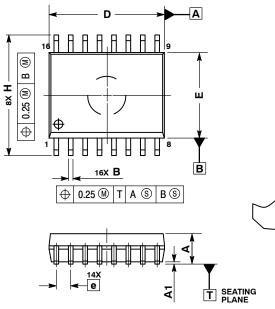
DOCUMENT NUMBER:	98ASB42431B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION: PDIP-16 PAGE 1 OF 1					
ON Semiconductor reserves the right the suitability of its products for any pa	to make changes without further notice to an articular purpose, nor does ON Semiconducto	stries, LLC dba ON Semiconductor or its subsidiaries in the United States y products herein. ON Semiconductor makes no warranty, representation r assume any liability arising out of the application or use of any product or icidental damages. ON Semiconductor does not convey any license under	or guarantee regarding r circuit, and specifically		



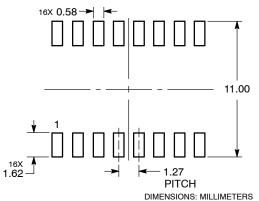


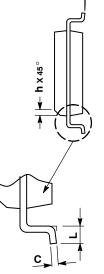






SOLDERING FOOTPRINT





SOIC-16 WB CASE 751G-03 **ISSUE D**

DATE 12 FEB 2013

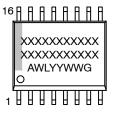
NOTES

A

- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION. З.
- MOLD PHOTHOSION. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN 4 5. EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN MAX			
Α	2.35	2.65		
A1	0.10	0.25		
в	0.35	0.49		
С	0.23	0.32		
D	10.15	10.45		
Е	7.40 7.60			
е	1.27	BSC		
н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
a	0 °	7 °		

GENERIC **MARKING DIAGRAM***



XXXXX = Specific Device Code А

- = Assembly Location
- = Wafer Lot WL
- YY = Year

WW = Work Week

= Pb-Free Package G

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " .", may or may not be present.

DOCUMENT NUMBER:	98ASB42567B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.					
DESCRIPTION: SOIC-16 WB PAGE 1 OF 1							
the suitability of its products for any pa	articular purpose, nor does ON Semiconducto	ON Semiconductor and where a set of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the					

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor date sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use a a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor houteds for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

Email Requests to: orderlit@onsemi.com

North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910 Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

SG3525ADW SG3525ADWG SG3525ADWR2 SG3525ADWR2G SG3525AN SG3525ANG